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**Field device integration (FDI®) –
Part 8: EDD to OPC-UA Mapping**

**Intégration des appareils de terrain (FDI®) –
Partie 8: Mapping de l'EDD avec l'OPC-UA**

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CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms, definitions, abbreviated terms, acronyms and conventions.....	8
3.1 Terms and definitions.....	8
3.2 Abbreviated terms and acronyms	8
3.3 Conventions.....	8
3.3.1 Capitalization.....	8
3.3.2 Graphical notation	8
4 Overview	10
5 Basic principles of explicit mapping	11
5.1 Semantic maps to tag EDD constructs	11
5.2 Alias collections.....	12
5.2.1 General	12
5.2.2 Syntax of semantic id for alias mappings	12
5.3 Namespace Alias Collection.....	12
5.4 Reference Type Alias Collection	14
5.5 Semantic maps for OPC-UA type mapping.....	16
5.5.1 General	16
5.5.2 Syntax of semantic Id for OPC-UA.....	16
5.6 Semantic maps for unit mapping	17
5.6.1 General	17
5.6.2 Syntax of semantic Id for Units.....	17
5.7 Explicit mapping of OPC-UA variable types.....	17
5.8 Explicit mapping of complex OPC-UA types	19
5.9 Explicit mapping of nested object and variable types	21
5.9.1 General	21
5.9.2 When to use collections.....	21
5.9.3 When to use menus	21
5.9.4 OPC-UA diagram of nested mapping example	21
5.9.5 EDD snippet of nested mapping example.....	22
5.10 Explicit mapping of methods	26
5.10.1 Mapping EDD methods to OPC-UA objects, variables or properties	26
5.10.2 Mapping EDD methods to OPC-UA methods.....	26
5.11 Explicit mapping of alarms	28
5.12 Explicit mapping of units	35
5.13 Explicit mapping of aggregated data by methods	36
5.14 Explicit mapping with reference types	38
5.14.1 General	38
5.14.2 Example: Adding an additional property to an instance of variable.....	39
5.14.3 Example: Adding an additional variable to an instance of a variable or an object	40
5.14.4 Example: Adding an OPC-UA alias to a variable	42
6 Implicit rules	44
6.1 BrowseName of OPC-UA object.....	44
6.1.1 General	44
6.1.2 Overruling of BrowseName implicit rule	44

6.2	DisplayName of OPC-UA object.....	44
6.2.1	General	44
6.2.2	Overruling of DisplayName implicit rule	44
6.3	HANDLING and AccessLevel	44
6.4	VALIDITY and availability.....	44
6.5	Return values of EDD methods	45
6.5.1	EDD methods mapped to OPC-UA objects, variables, properties or attributes	45
6.5.2	EDD methods mapped to OPC-UA methods	45
6.6	Units	45
6.7	Range.....	45
6.8	Forward cast.....	45
6.9	Backward cast	45
6.10	Abstract OPC-UA types.....	45
6.11	Unmapped mandatory OPC-UA properties, components and folders	46
6.12	Semantic Identifiers and Dictionary References	46
6.13	Implicit Type Casts for OPC-UA DataTypes	47
7	Mapping the EDD device model into PA-DIM (OPC 30081).....	48
7.1	General.....	48
7.2	Explicit mapping of sub-devices	48
7.3	Adding sub-devices.....	48
	Bibliography.....	52
	Figure 1 – OPC UA Graphical notation for NodeClasses	8
	Figure 2 – OPC UA Graphical notation for References.....	9
	Figure 3 – OPC UA Graphical notation example.....	9
	Figure 4 – Optimized Type Reference	10
	Figure 5 – Similarity of OPC-UA objects and EDD collections	10
	Figure 6 – Syntax of sematic ids for EDD entry points.....	12
	Figure 7 – Syntax of sematic id for alias mapping	12
	Figure 8 – Namespace Collection	14
	Figure 9 – Reference Type Collection	15
	Figure 10 – Use of SEMANTIC_MAP for OPC-UA types.....	16
	Figure 11 – Syntax of OPC-UA type identifier	16
	Figure 12 – Semantic map example	16
	Figure 13 – Syntax of Unit Identifier.....	17
	Figure 14 – Most simple mapping example	17
	Figure 15 – EDD variable mapped to an OPC-UA BaseDataVariableType.....	18
	Figure 16 – Simple mapping example with range and unit.....	19
	Figure 17 – Mapping of a collection to an OPC-UA variable	20
	Figure 18 – Nested objects and variables	22
	Figure 19 – Example of nested objects and variables.....	25
	Figure 20 – Simple method	26
	Figure 21 – Example of simple method mapping	28
	Figure 22 – Supported Alarms	32
	Figure 23 – Example of alarm mapping	35

Figure 24 – EDD example of explicit unit mapping 36

Figure 25 – Instance of PADIMType 37

Figure 26 – Method of type DD_STRING mapped to a string variable 38

Figure 27 – Adding a property which is not defined in mapped type 39

Figure 28 – EDD example of adding a property 40

Figure 29 – Adding a component 41

Figure 30 – EDD example adding a component 42

Figure 31 – Adding an alias 43

Figure 32 – EDD example adding an alias 43

Figure 33 – Explicit mapping of dictionary entries 46

Figure 34 – Combination with an implicitly mapped dictionary entry 47

Figure 35 – Subdevices 49

Figure 36 – Subdevices example 51

Table 1 – Alarm properties mapping 29

Table 2 – Implicit Type Casts 47

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Part 8: EDD to OPC-UA Mapping

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Draft	Report on voting
65E/851/CDV	65E/909/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

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FIELD DEVICE INTEGRATION (FDI®) –

Part 8: EDD to OPC-UA Mapping

1 Scope

This part of IEC 62769 specifies how the internal view of a device model represented by the EDD can be transferred into an external view as an OPC-UA information model by mapping EDD constructs to OPC-UA objects.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE For undated references, the edition of the referenced document (including any amendments), which applies for a specific FDI®¹ Technology Version is defined within the FDI® Technology Management Document and on the support portals of FieldComm Group and PI International.

IEC 61804-3, *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-8, *OPC Unified Architecture – Part 8: Data Access*

IEC 62541-9:2020, *OPC Unified Architecture – Part 9: Alarms and Conditions*

OPC 10000-17, *OPC Unified Architecture – Part 17: Alias Names*

OPC 10000-19, *OPC Unified Architecture – Part 19: Dictionary Reference*

IEC 62541-100, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-1, *Field Device Integration (FDI®) – Part 1: Overview*

IEC 62769-5, *Field Device Integration (FDI®) – Part 5: FDI® Information Model*

IEC 62769-6, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

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ISO/IEC 11179-6, *Information technology – Metadata registries (MDR) – Part 6: Registration*

OPC 30081, *Process Automation Devices – PADIM*

UN/CEFACT, UNECE Recommendation 20, *Codes for Units of Measure Used in International Trade*
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3 Terms, definitions, abbreviated terms, acronyms and conventions

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1, IEC 62769-5, IEC 62769-6, IEC 62541-3, IEC 62541-4, IEC 62541-5, IEC 62541-8, IEC 62541-9, OPC 10000-17, IEC 62541-100, and OPC 30081 apply.

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- ISO Online browsing platform: available at <https://www.iso.org/obp>

3.2 Abbreviated terms and acronyms

For the purposes of this document, the abbreviated terms and acronyms given in IEC 62769-1 as well as the following apply.

PA-DIM Process Automation Device Information Model

3.3 Conventions

3.3.1 Capitalization

Capitalization of the first letter of words is used in the IEC 62769 series to emphasize an FDI® defined term.

3.3.2 Graphical notation

OPC UA defines a graphical notation for an OPC UA AddressSpace. It defines graphical symbols for all NodeClasses and how different types of References between Nodes can be visualized. Figure 1 shows the symbols for the NodeClasses used in this document. NodeClasses representing types always have a shadow.

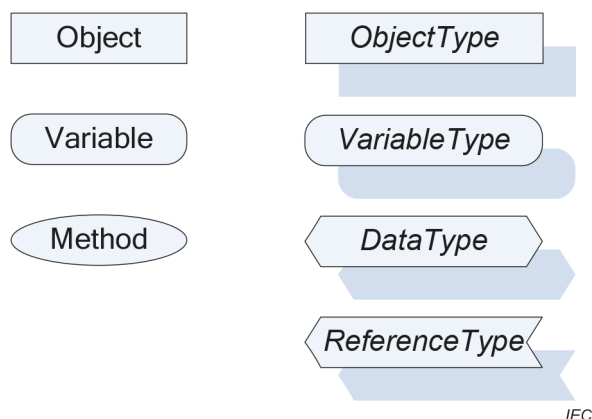
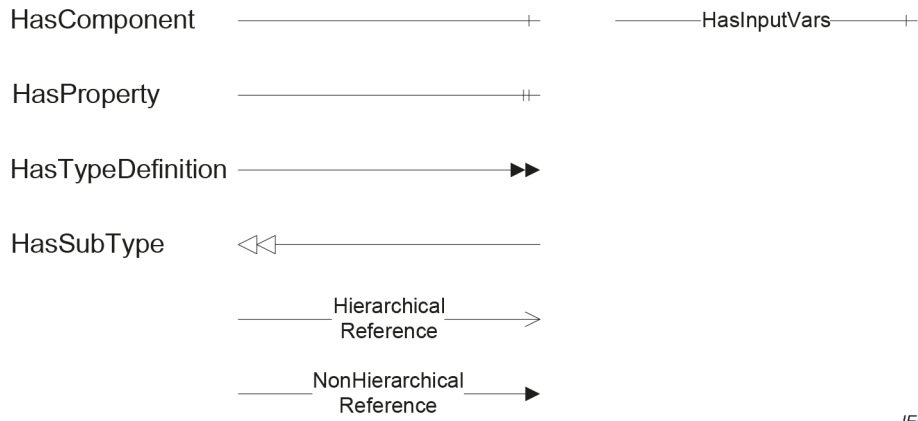


Figure 1 – OPC UA Graphical notation for NodeClasses

Figure 2 shows the symbols for the ReferenceTypes used in this document. The Reference symbol is normally pointing from the source Node to the target Node. The only exception is the HasSubType Reference. The most important References such as HasComponent, HasProperty, HasTypeDefinition and HasSubType have special symbols avoiding the name of the Reference. For other ReferenceTypes or derived ReferenceTypes, the name of the ReferenceType is used together with the symbol.



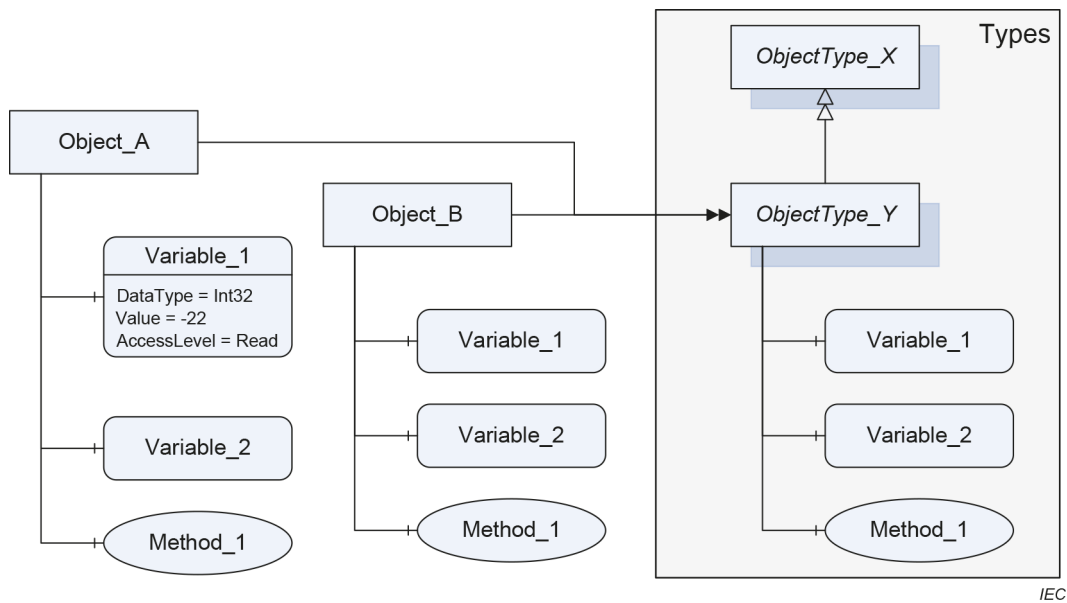
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Figure 2 – OPC UA Graphical notation for References

Figure 3 shows a typical example for the use of the graphical notation. Object_A and Object_B are instances of the ObjectType_Y indicated by the HasTypeDefinition References. The ObjectType_Y is derived from ObjectType_X indicated by the HasSubType Reference. The Object_A has the components Variable_1, Variable_2 and Method_1.

To describe the components of an Object on the ObjectType, the same NodeClasses and References are used on the Object and on the ObjectType such as for ObjectType_Y in the example. The Nodes used to describe an ObjectType are instance declaration Nodes.

To provide more detailed information for a Node, a subset or all Attributes and their values can be added to a graphical symbol (see for example Variable_1, the component of Object_A in Figure 3).



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Figure 3 – OPC UA Graphical notation example

To improve readability, this document frequently includes the type name inside the instance box rather than displaying both boxes and a reference between them. This optimization is shown in Figure 4.

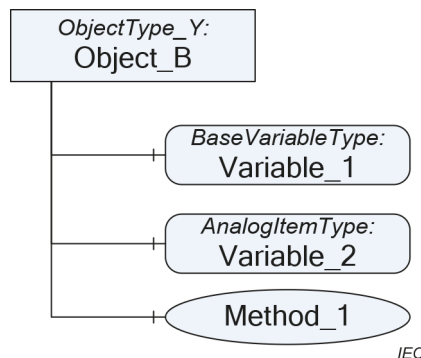


Figure 4 – Optimized Type Reference

4 Overview

There are two types of mapping mechanisms – explicit and implicit mapping. Explicit mapping is provided by the EDD constructs SEMANTIC_MAP in combination with COLLECTIONS, METHODS and VARIABLES including the mapping of enumerations and is done by the EDD-developer. Implicit mapping is provided by the implementation of the OPC-UA server in conjunction with a FDI® Server and covers definitions like default casts (e.g. any number value to float64) or even the mapping of complete lists of unit codes from a fieldbus domain (HART HART®², PROFIBUS®³, ...) into an OPC-UA domain (e.g. UNECE, CDD, ...).

Looking at OPC-UA objects containing named data items like attributes, properties, variables and other objects, the most similar EDD objects are collections containing named data items like variables, menus and other collections (see Figure 5).



Figure 5 – Similarity of OPC-UA objects and EDD collections

In fact, the EDD construct collection is the key element for the basic principle of how EDD device model data shall be mapped into an OPC-UA information model. The following clauses

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describe and define how this shall be done. Therefore, this document has normative character for EDD developers and developers of OPC-servers accessing an FDI® Server to publish an OPC-UA information model according to a specific OPC-UA namespace and the mapping information provided by the EDD.

Clause 5 covers in detail how the mapping works in principle and for any OPC-UA information model based on any namespace.

Based on Clause 5, Clause 7 describes some details how to map the EDD into PA-DIM. Additional normative definitions how to map fieldbus specific data (e.g. identification) into PA-DIM is provided by the FDI-Profile specifications for HART, FF, PROFINET®⁴, PROFIBUS, Modbus®⁵ and ISA100 Wireless®⁶.

Before starting with doing some EDD mapping, it is strongly recommended to get a basic understanding of OPC-UA concerning how object types, variable types and reference types are defined.

5 Basic principles of explicit mapping

5.1 Semantic maps to tag EDD constructs

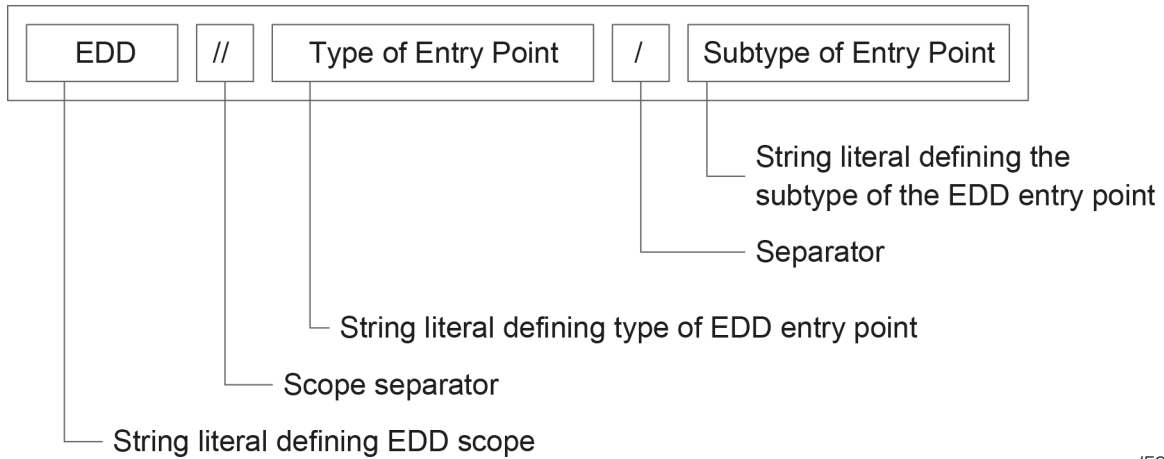
For not having to use naming conventions for EDD constructs to link a specific purpose to an EDD construct, semantic maps shall be used to kind of tag an EDD construct by a specifically defined semantic id. For the time being, three syntax definitions exist for three specific purposes. The details of how to use them will be explained in the corresponding context.

The syntax of semantic ids for EDD entry points is illustrated in Figure 6.

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Figure 6 – Syntax of semantic ids for EDD entry points

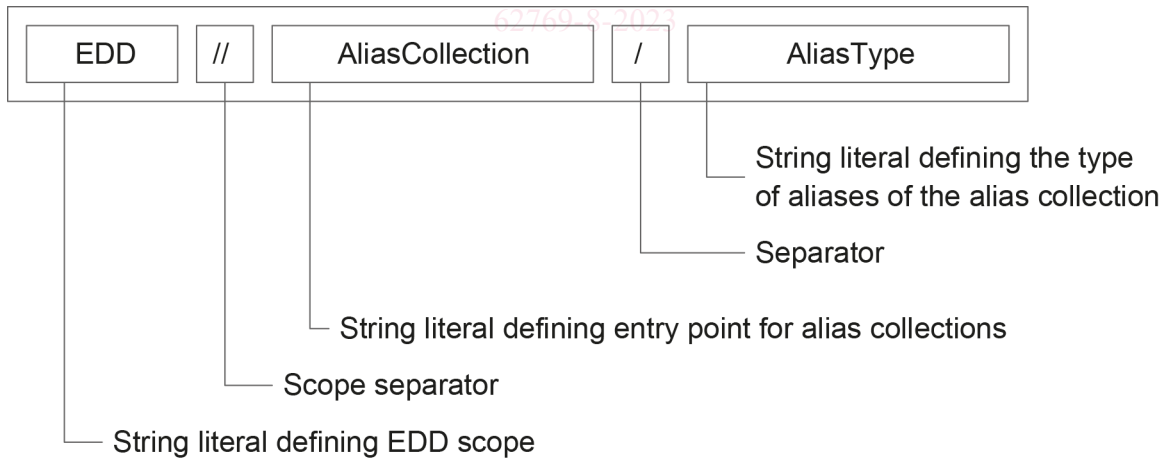
5.2 Alias collections

5.2.1 General

Alias collections are used to define aliases for lengthy strings having a specific meaning. The alias should be short and shall be unique across the complete EDD. Aliases will be used as member identifiers or as a part of member identifiers or in SEMANTIC_MAPs for OPC-UA type mapping. Alias collections are the main entry points to resolve EDD to OPC-UA mapping and shall not depend on each other (see 5.3 and 5.4).

5.2.2 Syntax of semantic id for alias mappings

The syntax of semantic id for alias mapping is illustrated in Figure 7.



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Figure 7 – Syntax of semantic id for alias mapping

5.3 Namespace Alias Collection

To prevent name conflicts, any OPC-UA type is defined in scope of a specific namespace. A namespace collection and appropriate variables shall be defined to provide suitable names for the namespace URIs. The member identifier of the collection item shall be used as an alias wherever a namespace identifier is needed. In the following example "__UA_" represents the namespace <http://opcfoundation.org/UA/> which is defined by the default value of the referenced variable "UA_Namespace".

It is mandatory to define at least one namespace collection for an EDD defining EDD to OPC-UA mapping.

Definition:

The name of the namespace collection shall be tagged by a SEMANTIC_MAP with the following semantic ID:

"EDD//AliasCollection/Namespaces"

The name of the namespace COLLECTION, the name of the SEMANTIC_MAP and the names of the referenced string variables can be freely chosen. The default value of the referenced string variable shall contain a valid namespace.

Figure 8 shows an EDD namespace Collection example.

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